Description

The 10N65 can be used in various power swithching circuit for system miniaturization and higher efficiency. The package form is TO252-2L, which accords with the RoHS standard.

D G S

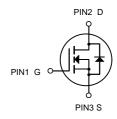
TO252-2L

General Features

 $V_{DS} = 650 \text{ V}, I_D = 10 \text{ A}$ $R_{DS(ON)} < 1.05 \Omega \text{ W}_{GS} = 10 \text{ V}$

Application

Power switch circuit of adaptor and charger. Electronic lamp ballast



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Units Tube
10N65	TO252-2L	10N65 XXX YYYY	2500

Absolute Maximum Ratings@T_i=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	650	V
VGS	Gate-Source Voltage	<u>+</u> 30	V
I _D @T _C =25°C	Drain Current, V _{GS} @ 4.5V	10	А
I _D @T _C =100°C	Drain Current, V _{GS} @ 4.5V	6.3	А
IDM	Pulsed Drain Current ¹	40	А
P _D @T _C =25°C	Total Power Dissipation	45	W
Eas	Single Pulse Avalanche Energy ⁴	500	mJ
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C



Electrical Characteristics (T_J=25 °C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristic		•		•	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	650	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =650V, V _{GS} =0V	-	-	1.0	μΑ
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±30V	-	-	±100	nA
On Charac	eteristics					
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.0	1.5	4.0	V
$R_{\text{DS(on)}}$	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =5A	-	0.72	0.95	Ω
Dynamic C	Characteristics		•			
C _{iss}	Input Capacitance	\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	1570	-	pF
Coss	Output Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	166	-	pF
C _{rss}	Reverse Transfer Capacitance		-	18	-	pF
Qg	Total Gate Charge	V _{DS} =520 V, I _D =10A,	-	44	-	nC
Q_gs	Gate-Source Charge	V_{GS} =320 V, ID=10A, V_{GS} =10V	-	6.7	-	nC
Q_gd	Gate-Drain("Miller") Charge	VGS 10 V	-	18.5	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-on Delay Time		-	23	-	ns
tr	Turn-on Rise Time	V_{DD} = 325 V, R_L =25 Ω	-	69	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	V_{GS} =10V, R_{REN} =3 Ω	-	144	-	ns
t_f	Turn-off Fall Time		-	77	-	ns
Drain-Sou	rce Diode Characteristics and Maxin	num Ratings				
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	10	А
I _{SM}	Maximum Pulsed Drain to Source Did	ode Forward Current	-	-	40	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = 10A	-	-	1.4	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition : T_J =25 °C , V_{DD} =20V, V_G =10V,L=0.5mH,Rg=25 Ω , I_{AS} =7.2A T_J =25 °C , V_{DD} =-20V, V_G = -10V,L=0.5mH,Rg=25 Ω , I_{AS} =-8.4A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



Typical Characteristics

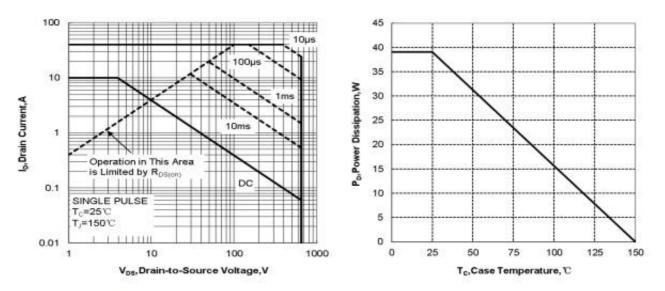


Figure.1 Maximum Forward Bias Safe Operating Area Figure.2 Maximum Power Dissipation vs Case Temperature

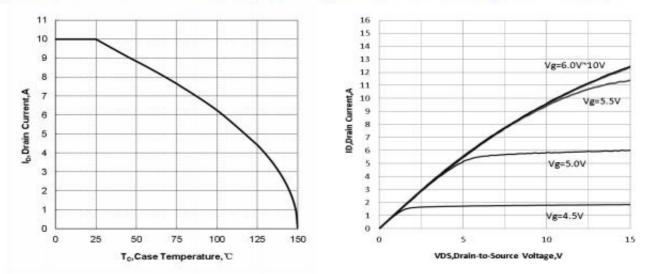
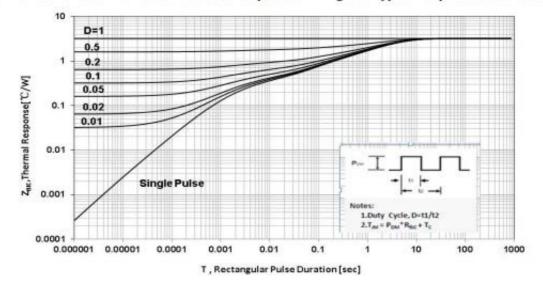
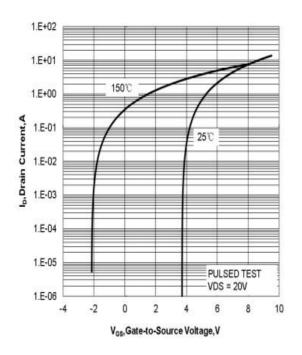


Figure.3 Maximum Continuous Drain Current vs Case Temperature Figure.4 Typical Output Characteristics





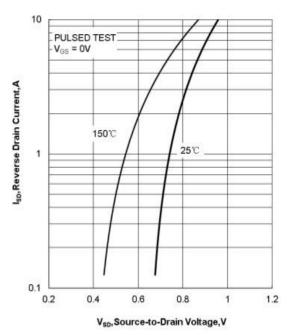


Figure.6 Typical Transfer Characteristics

Figure.7 Typical Body Diode Transfer Characteristics

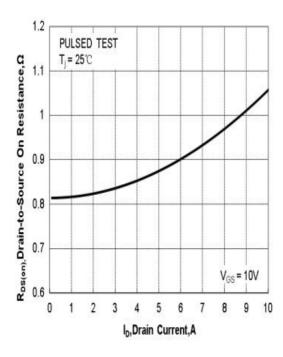


Figure 8 Typical Drain to Source ON Resistance vs Drain Current

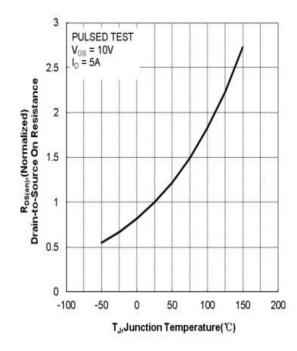
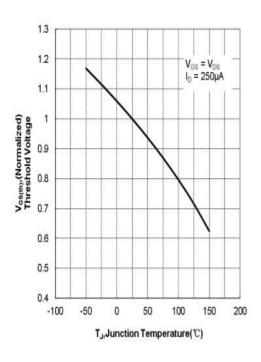


Figure.9 Typical Drian to Source on Resistance vs Junction Temperature



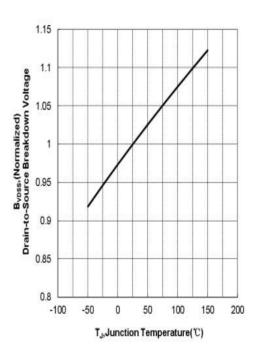
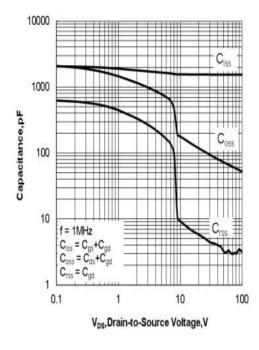


Figure 10 Typical Theshold Voltage vs Junction Temperatur

Figure 11 Typical Breakdown Voltage vs Junction Temperature



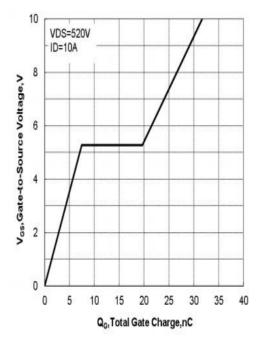
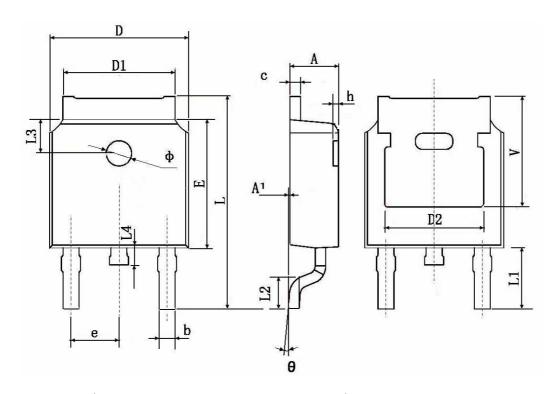


Figure 12 Typical Capacitance vs Drain to Source Voltage

Figure.13 Typical Gate Charge vs Gate to Source Voltage



TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483	0.483 TYP.		TYP.	
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600	TYP.	0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		



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